



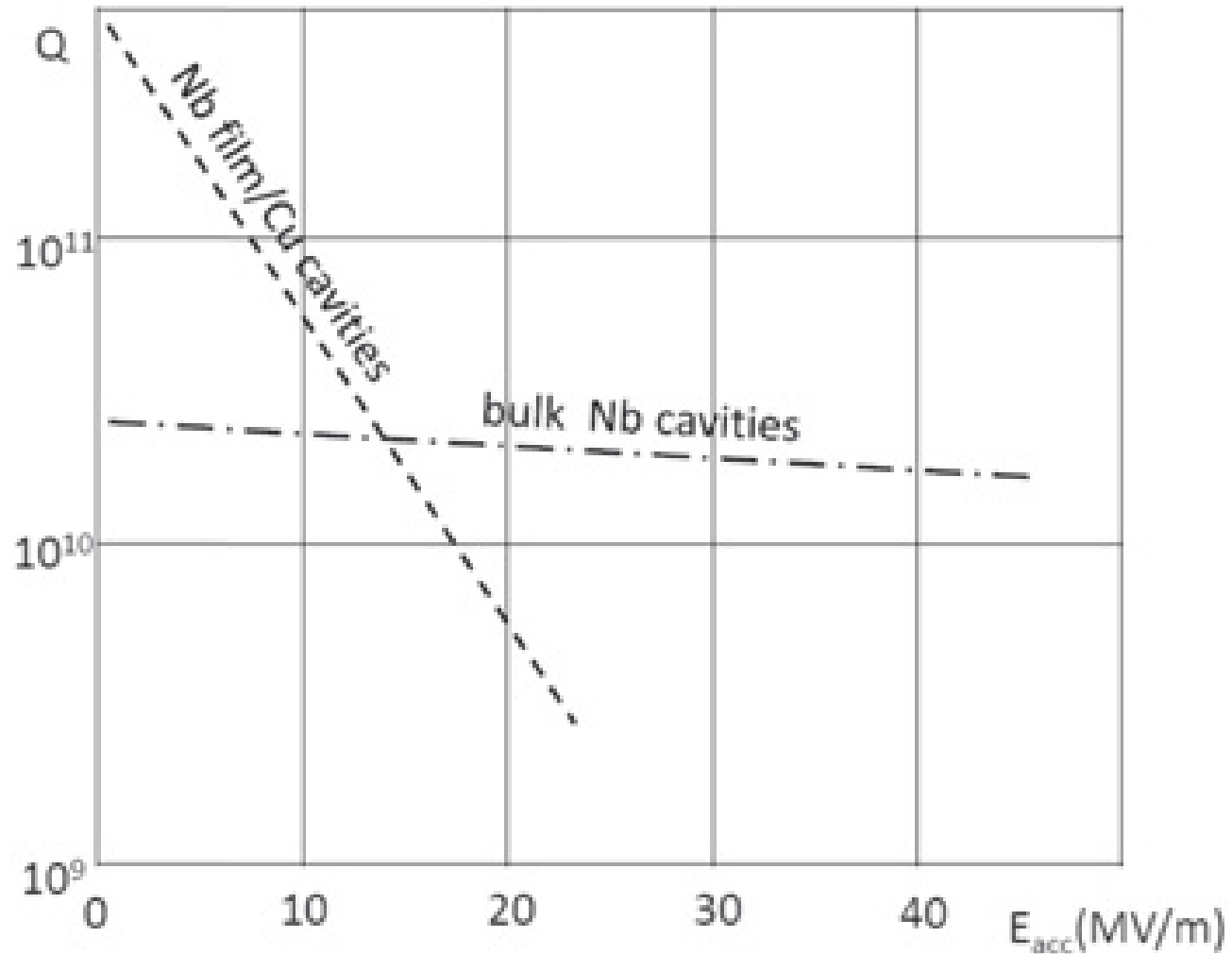
The way of thick films toward a flat Q in sputtered cavities



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The Q slope in thin film sputtered cavities

(@ 1.5 GHz and 1.8 K)



Part 1

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Why thick films?

The Experimental Evidence

- **Nb sputtered Cu:** **Display Q-slope**
- **Nb clad Cu:** **No Q-slope**

In what clad cavities differ from sputtered ones?

- **Nb Thickness** → Bulk-like properties:
 - **film purity**
 - **grain size** → High RRR
- **Nb-Cu Interface** → Explosively interdiffused material

**How Nb thickness could
affect RF performances?**

1. Possible Physical mechanism:

Superconducting gap depends on n_s/n

$$\Delta = \Delta_0 - P_F V_S$$

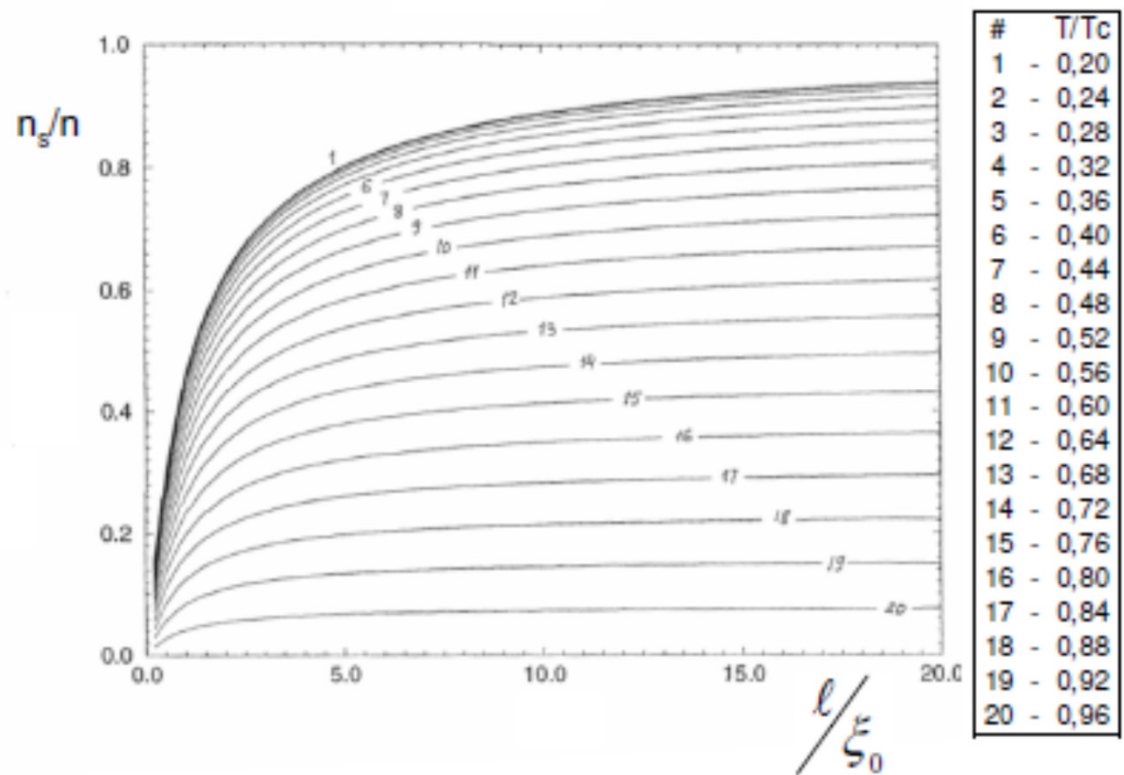
$$V_S = V_S (n_s/n)$$

V. Palmieri, "The Problem of Q-drop In Superconducting Resonators Revised by the Analysis of Fundamental Concepts from Rf-superconductivity Theory" Proceedings of the 12th International Workshop on RF Superconductivity, Cornell University, Ithaca, New York, (2005) USA

1. Possible Physical mechanism:

Superconducting gap depends on n_s/n

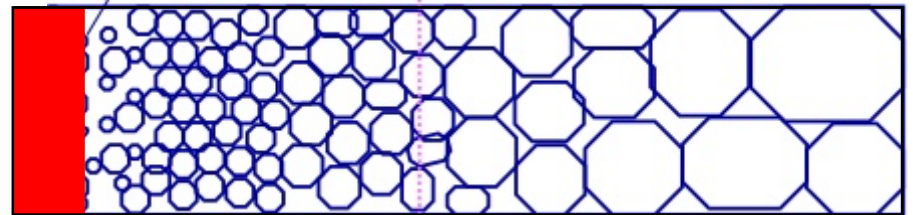
$$\frac{n}{n_s} = \cot gh \left(\frac{l}{\xi_0} \right)$$



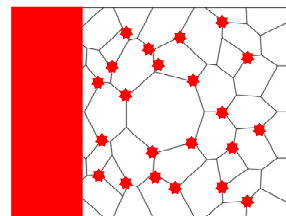
High Nb Thickness can provide $RRR > 100$

because of

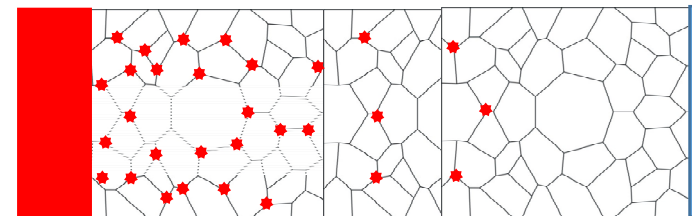
- Large grain growth



- The film top layer is farther from Nb/Cu Interface



a)



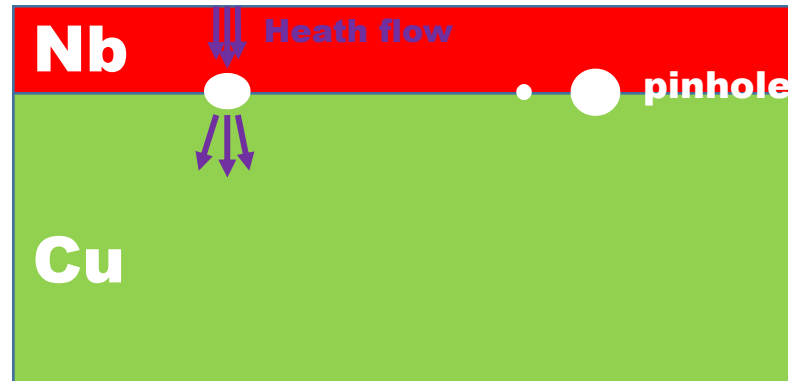
b)

(the larger thickness damps impurity diffusion from interface)

2. Possible Physical mechanism

Suggested by S. Calatroni from CERN:

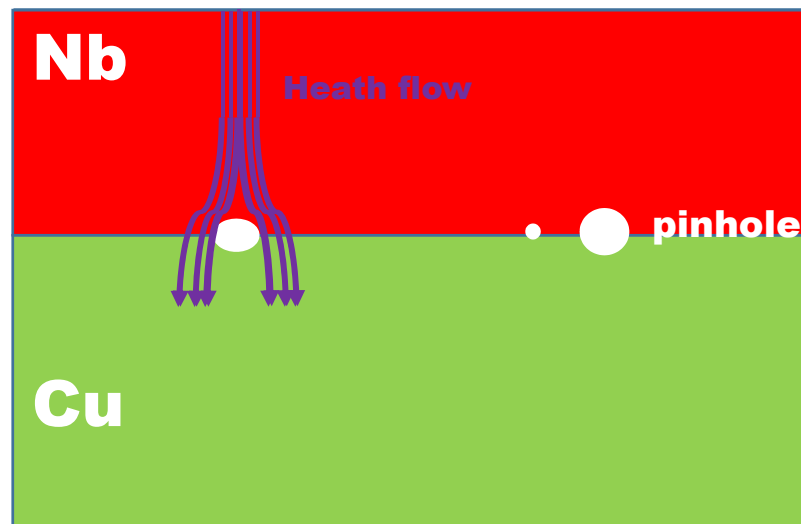
In **thin** films, in a case of a defect, the thermal flow propagates from Nb to Cu almost one-dimensionally



2. Possible Physical mechanism

Suggested by S. Calatroni from CERN:

In **thick films, the thermal flow shunts the defect, propagating from Nb to Cu with higher efficiency**



3. Possible Physical mechanism

A defected thermal contact at **the Nb-Cu interface is responsible of **the Q-slope****

3. Possible Physical Mechanism

The **quality of interface**

depend on film stress,

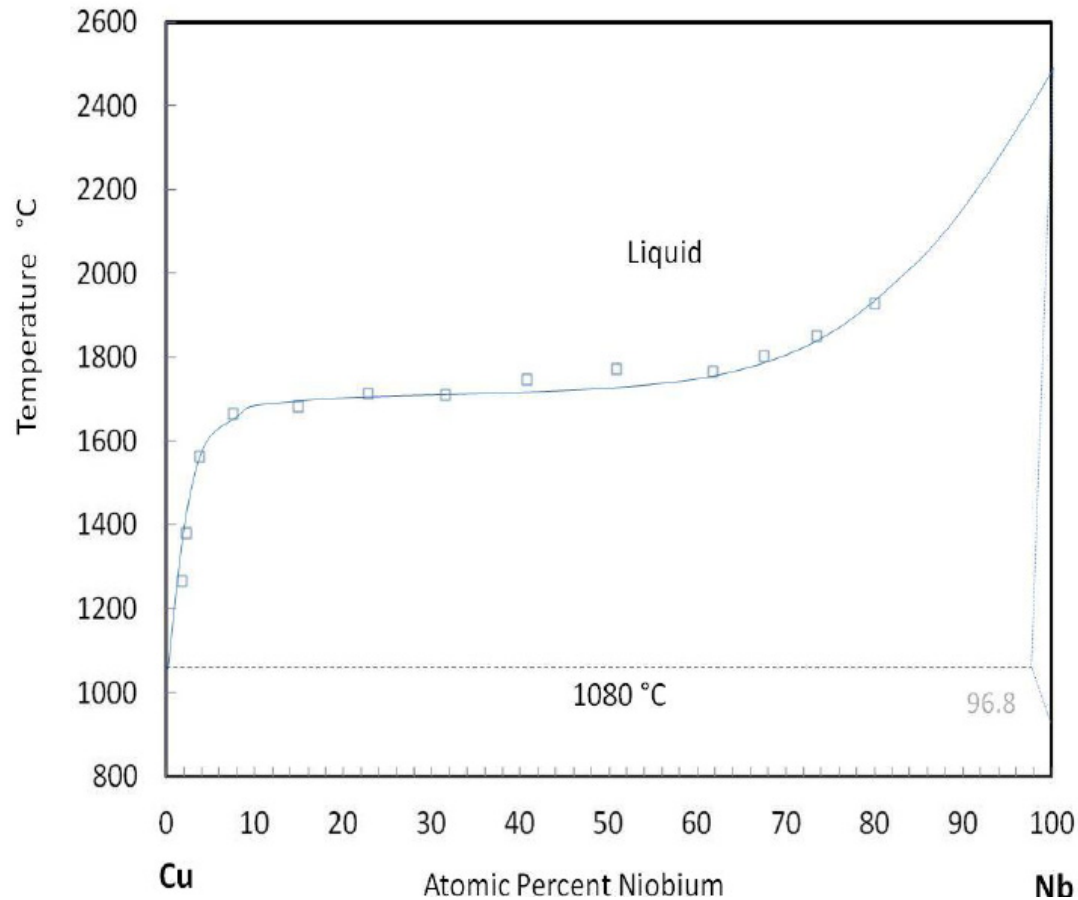
.....

even more if Nb and Cu are not miscible!!

3. Possible Physical mechanism

The Cu-Nb phase diagram

(after D.J. Chakrabarti and D.E. Laughlin)



3. Possible Physical Mechanism

Only if **the film is not stressed**, one will be sure that a **thick film** will be **adherent to the interface**

Hence,

**There are different considerations pushing to try
to deposit **thick films** rather than **thin films****

because eventually,

thick films imply:

- **higher purity**
- **better interface**

Part 2

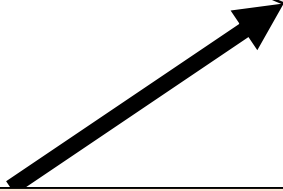
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Experimental procedure

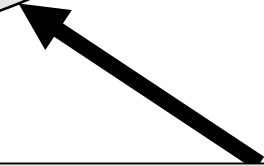
**Sputtering
pressure**



**Zero-stress
films**

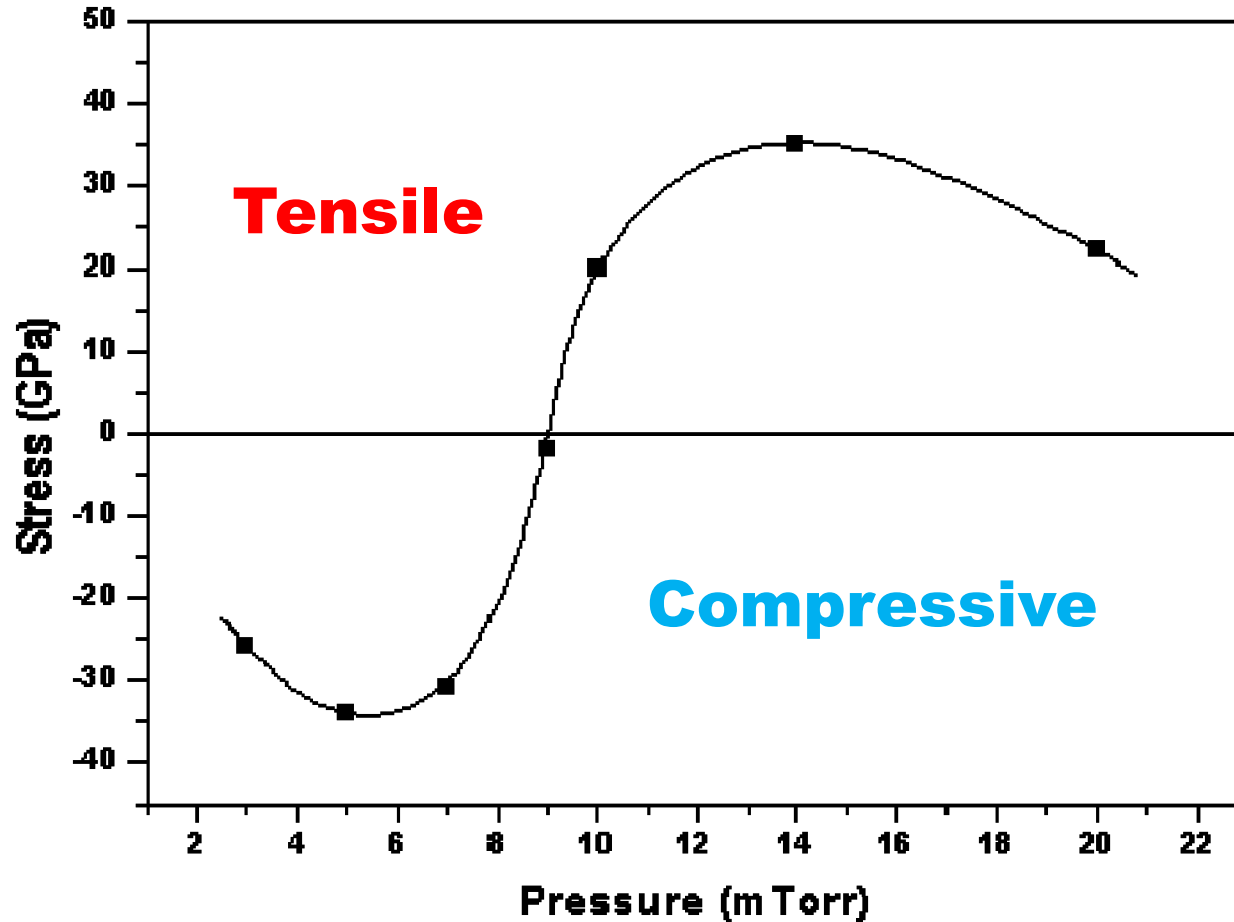


**Substrate
temperature**



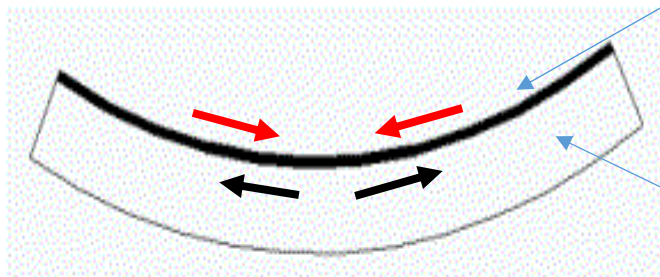
**film
thickness**

Stress in thin films



Stress in thin films

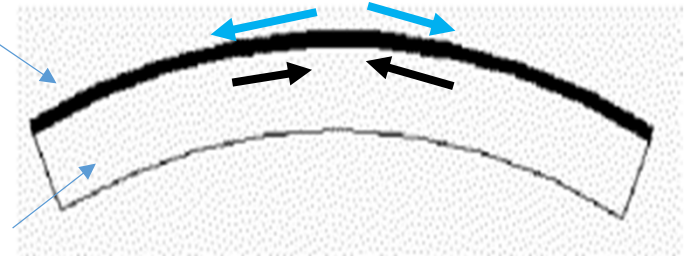
Tensile Stress



Film

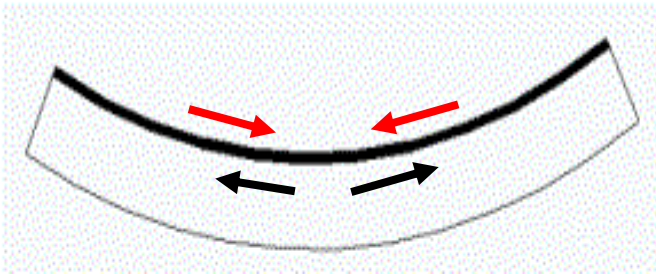
Substrate

Compressive Stress



Stress in thin films

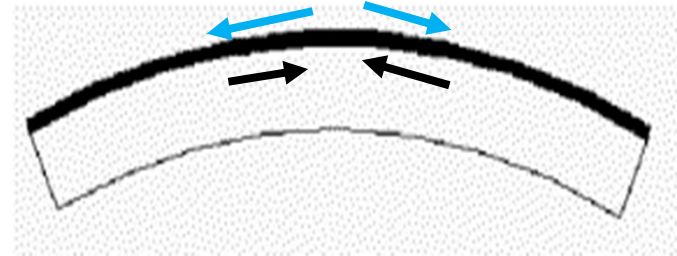
Tensile Stress



Film is smaller than substrate.

In order to grow onto the substrate the film must adapt to it under **tensile forces**

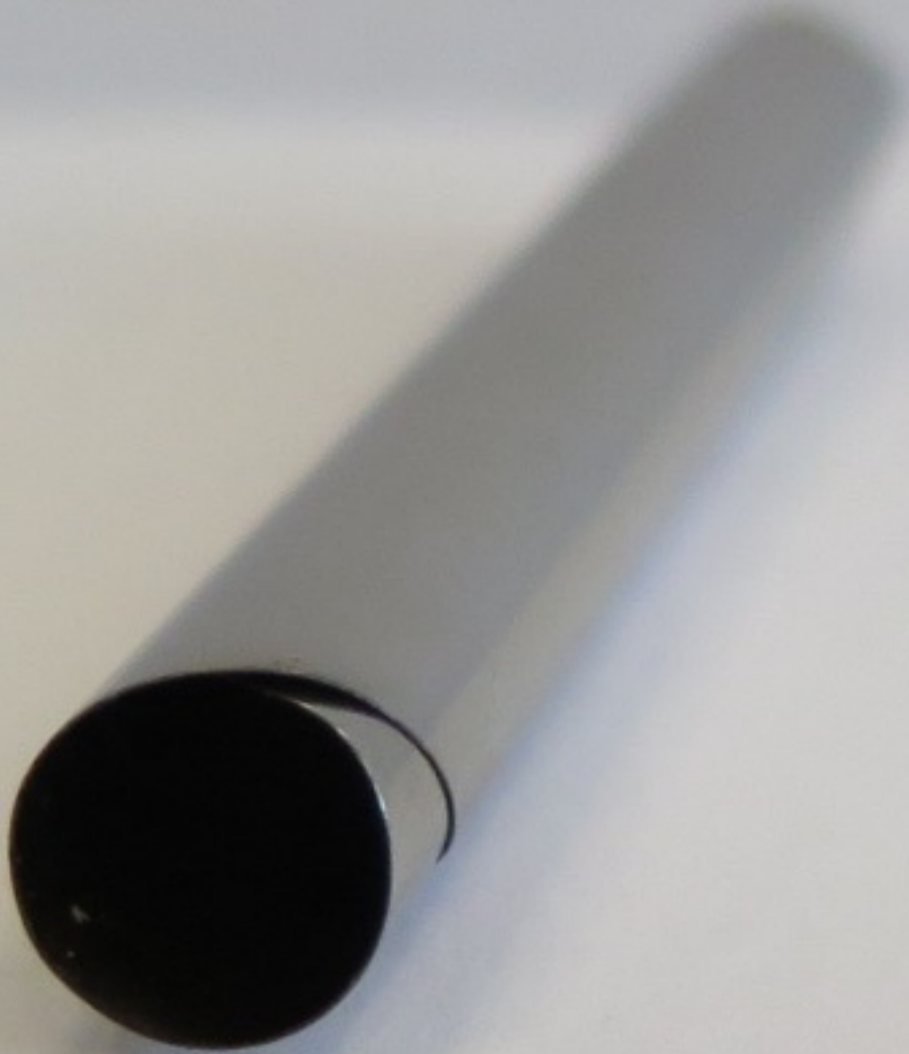
Compressive Stress



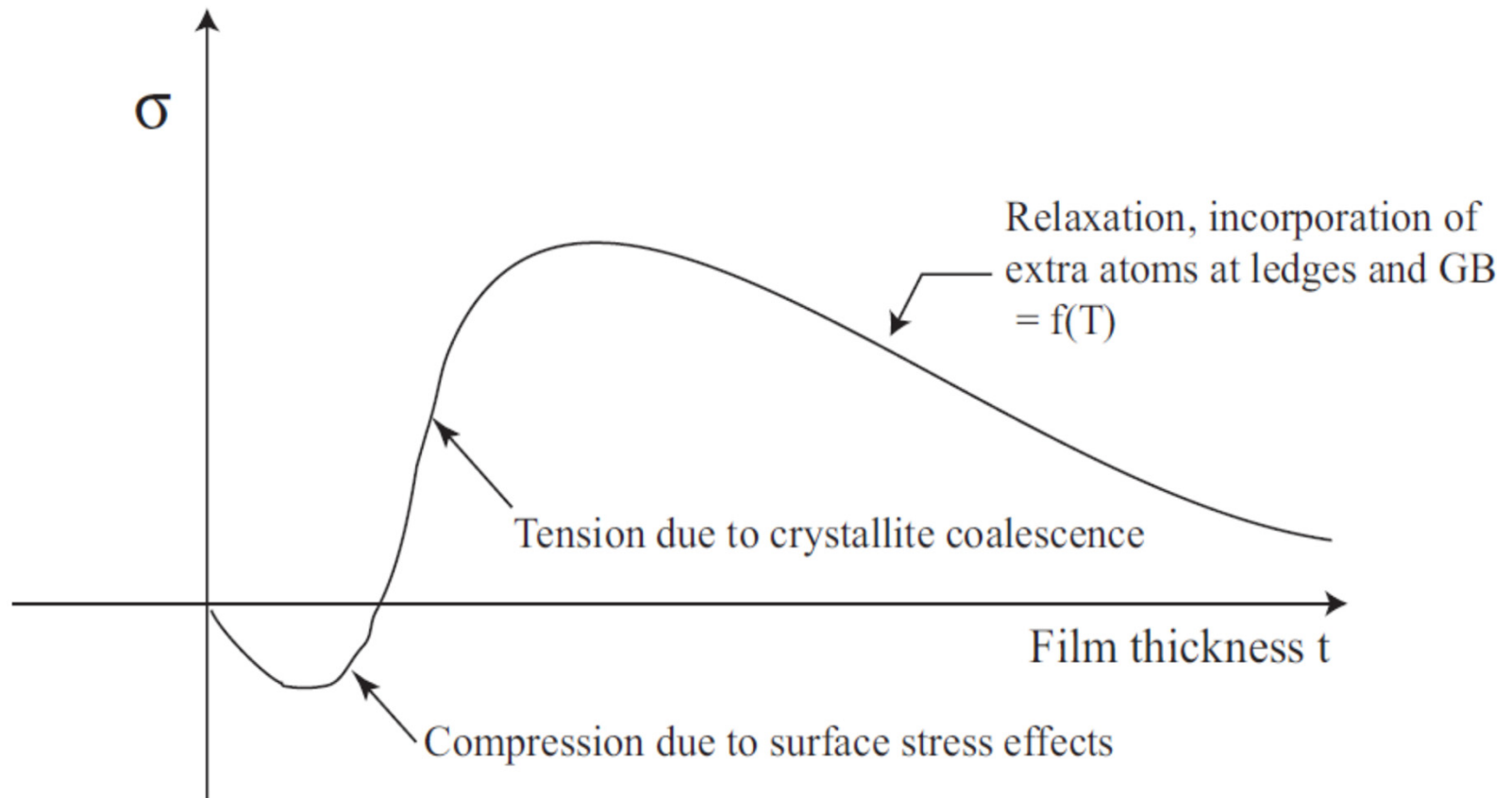
Film is larger than substrate.

In order to grow on the substrate, the film must adapt to it under **compressive forces**

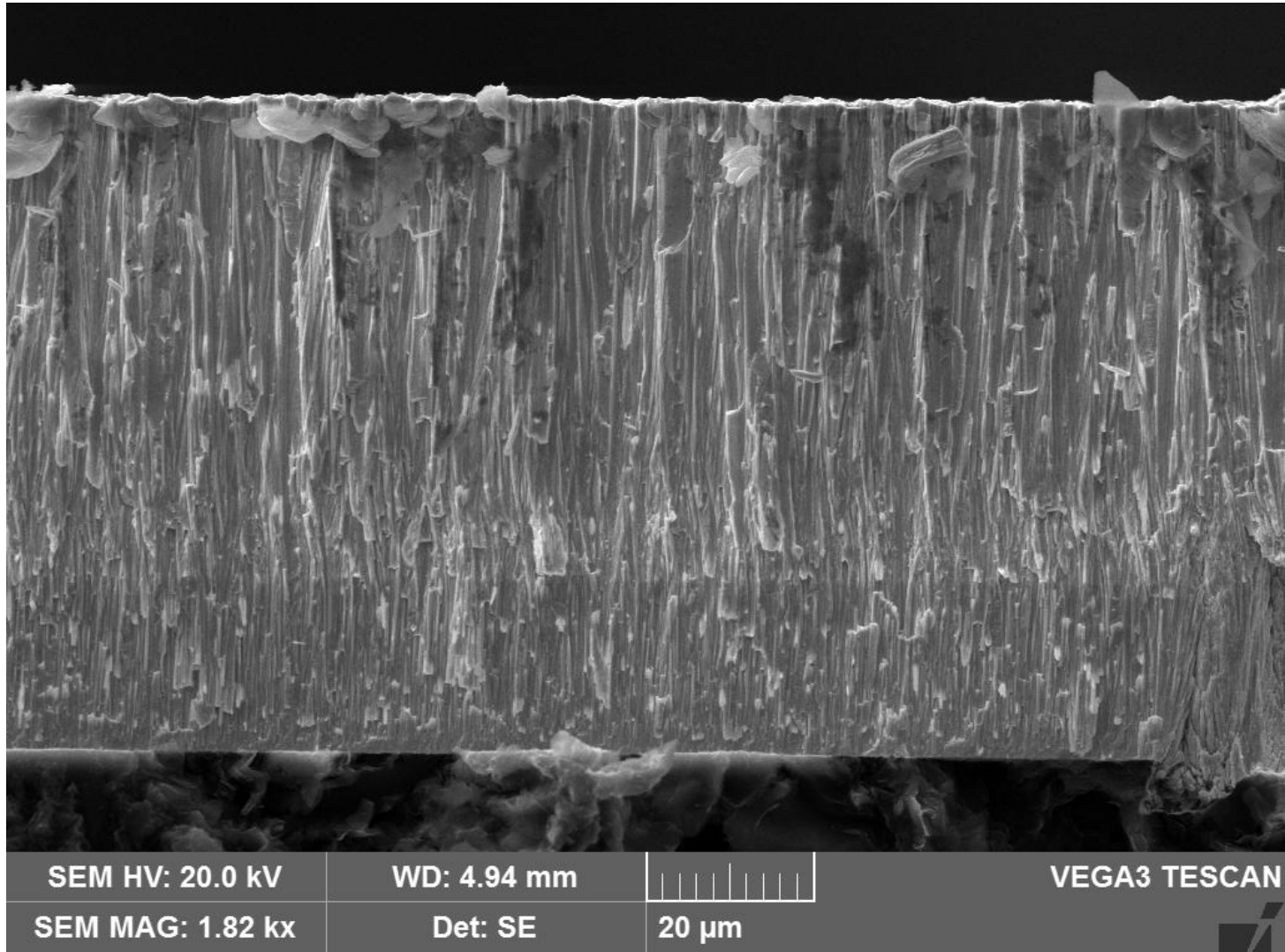
How to measure the film stress?



Film stress versus film Thickness



A new sputtering method to obtain hundreds micron thick Nb films



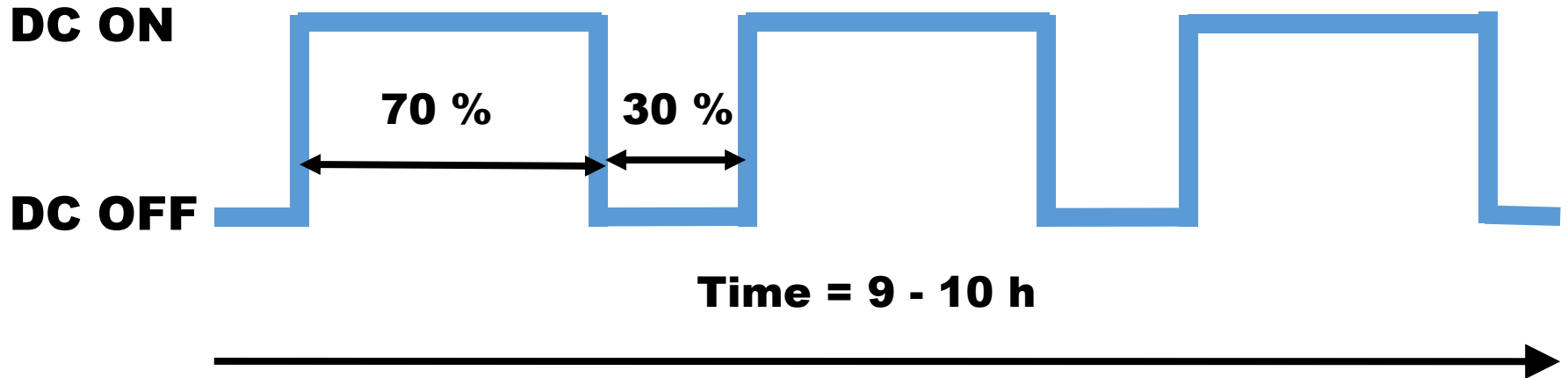
You deposit a thin layer of a few hundreds of nanometers,

than you stop the process,

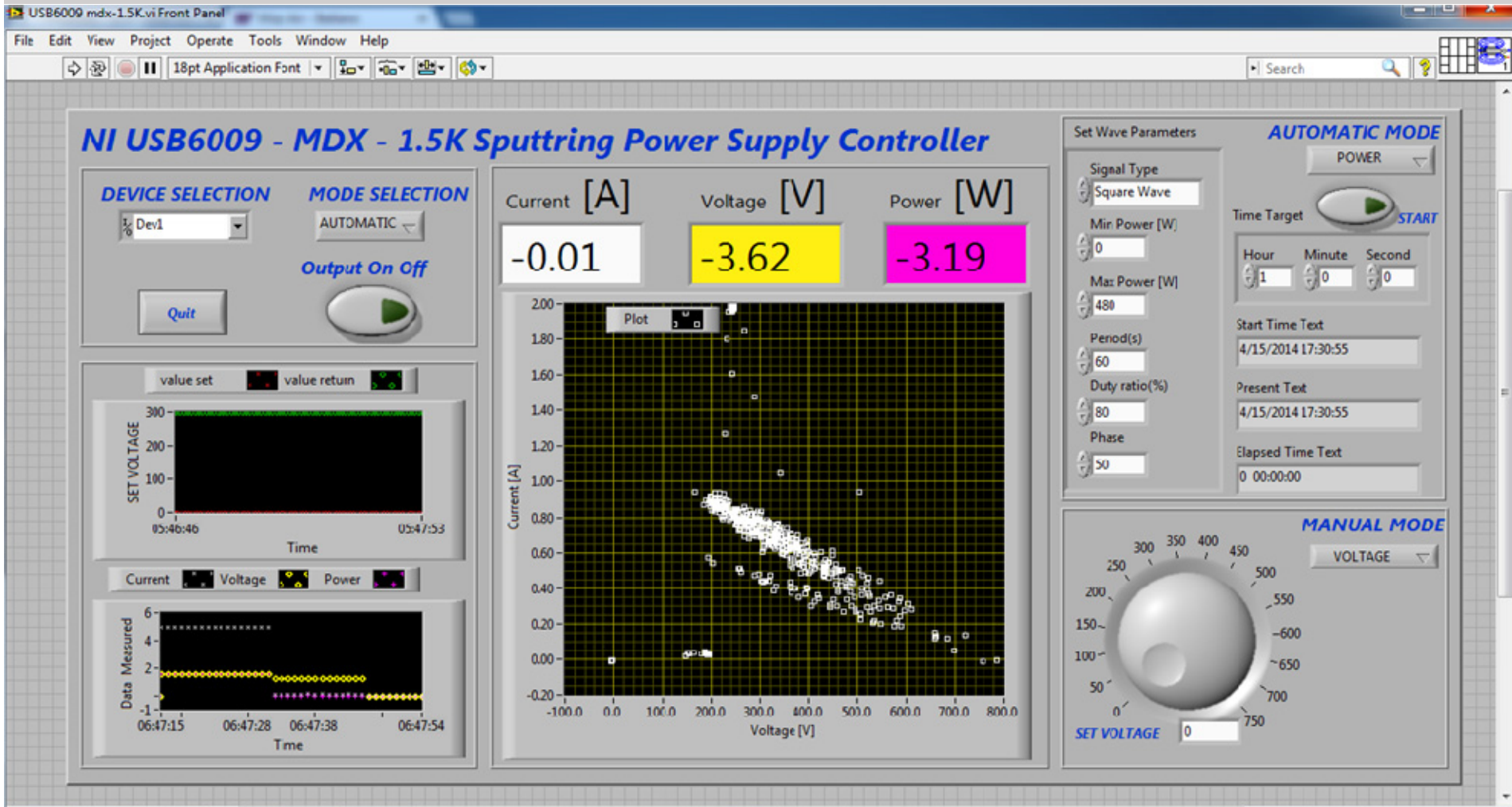
giving to the film the time to renormalize.

**Then you deposit the new layer on the old one,
and so on for thousands of times as in ALD**

Thick film as multilayers



A 70 micron film is made of 350 layers of 200 nanometers

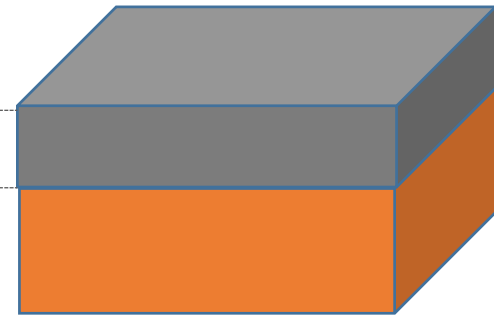


Multilayer deposition Parameters

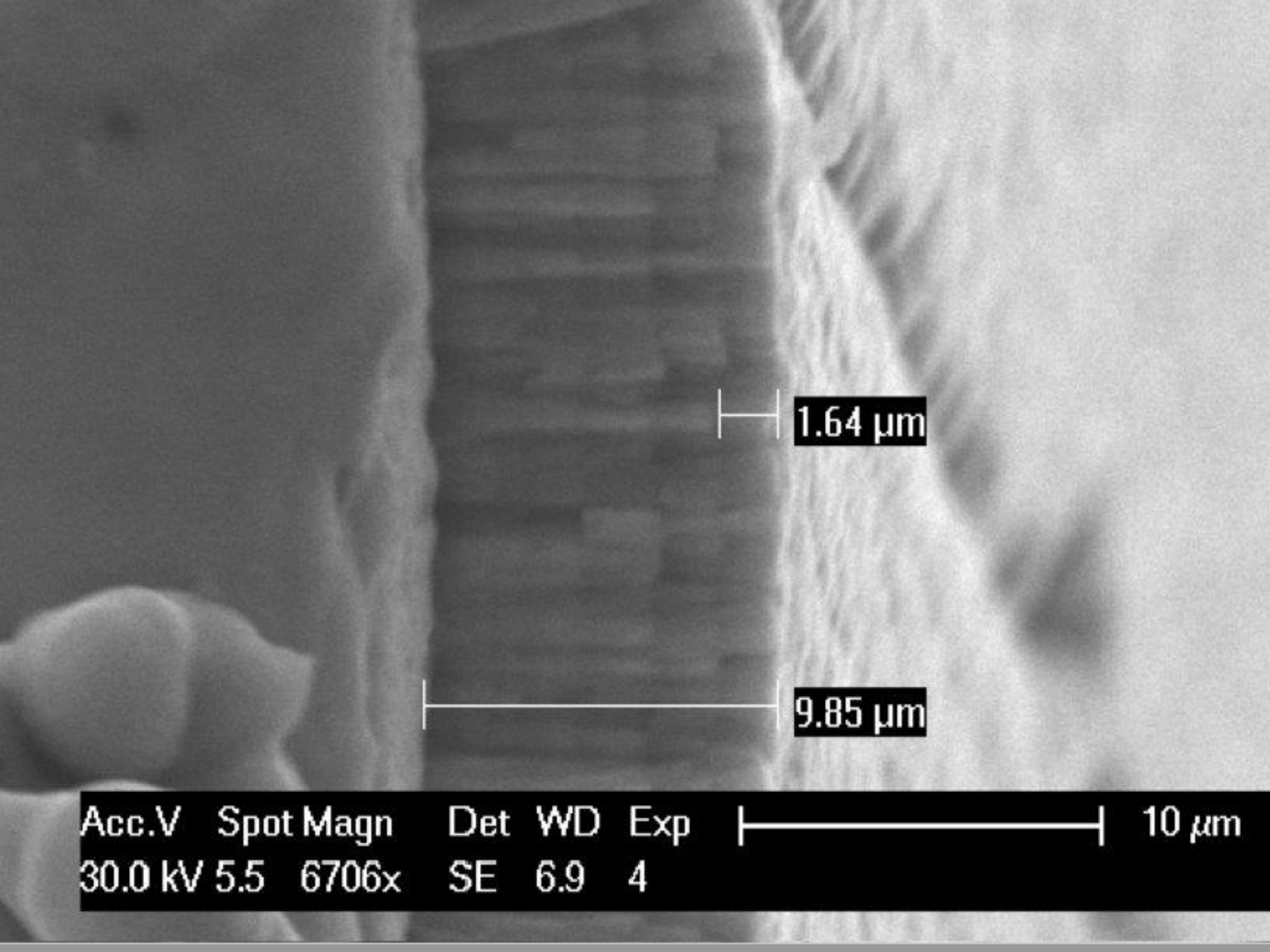


Single Layer Thickness = **100, 300, 400, 500 nm**

Total Thickness (on the cell) = **70 μm**



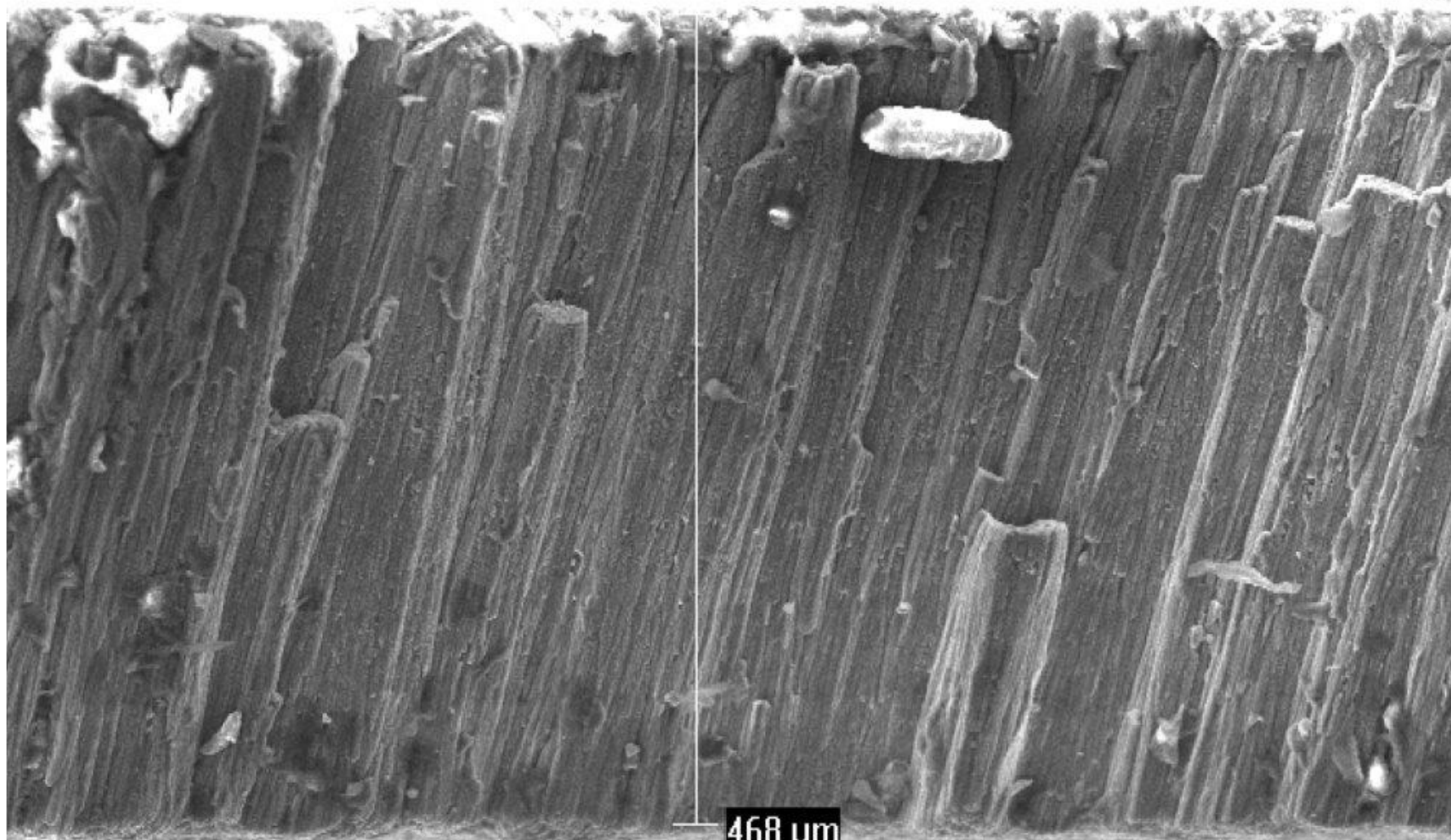
Deposition Rate = **3 nm/s**



1.64 μm

9.85 μm

Acc.V	Spot	Magn	Det	WD	Exp	10 μm
30.0 kV	5.5	6706x	SE	6.9	4	



Acc.V	Spot	Magn	Det	WD	Exp	200 μm
20.0 kV	4.5	350x	SE	9.4	4	6.1GHz Anello Etch

**Last film
sputtered
was 1,2 mm
thick!!!**

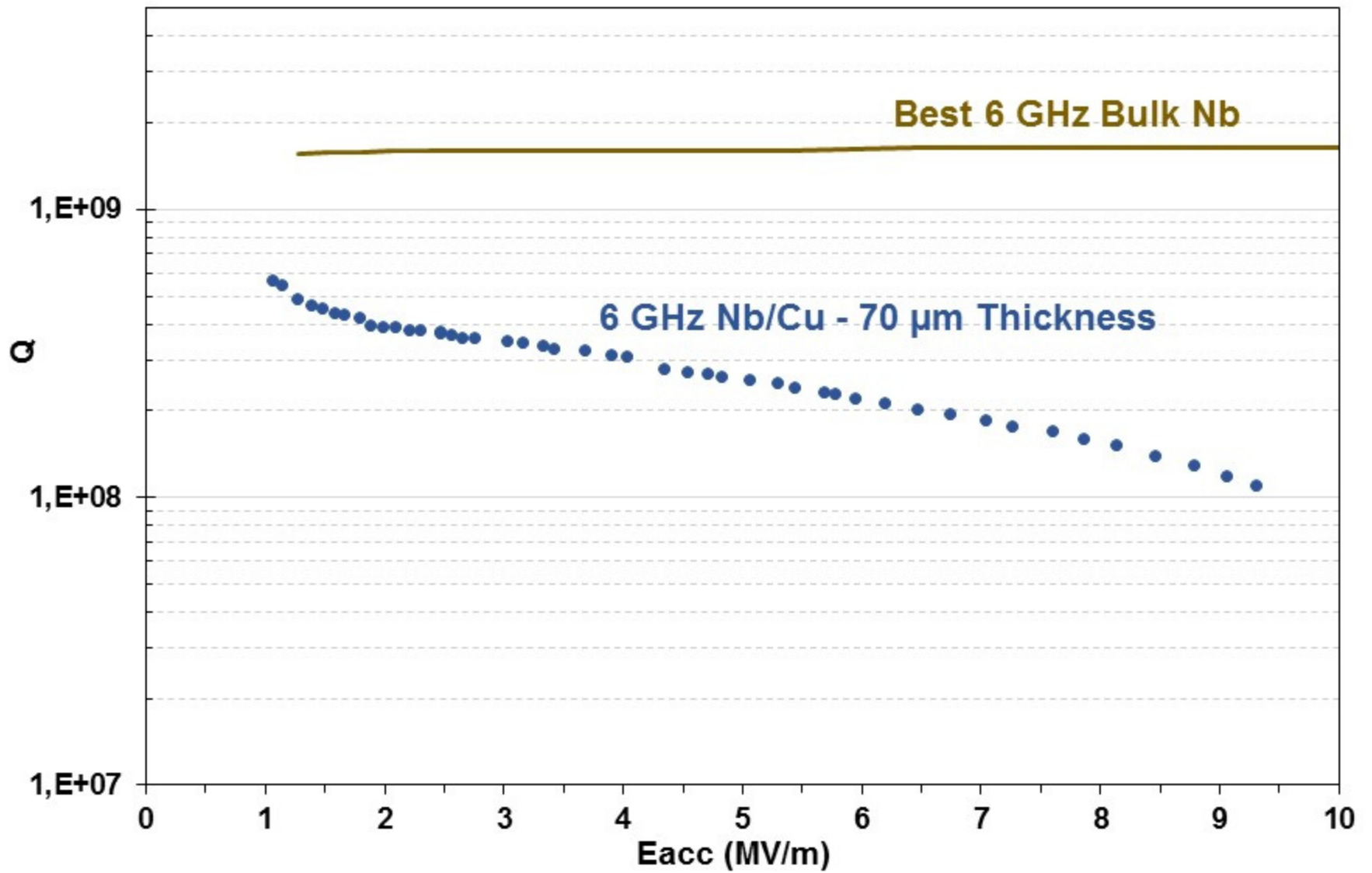


Part 3

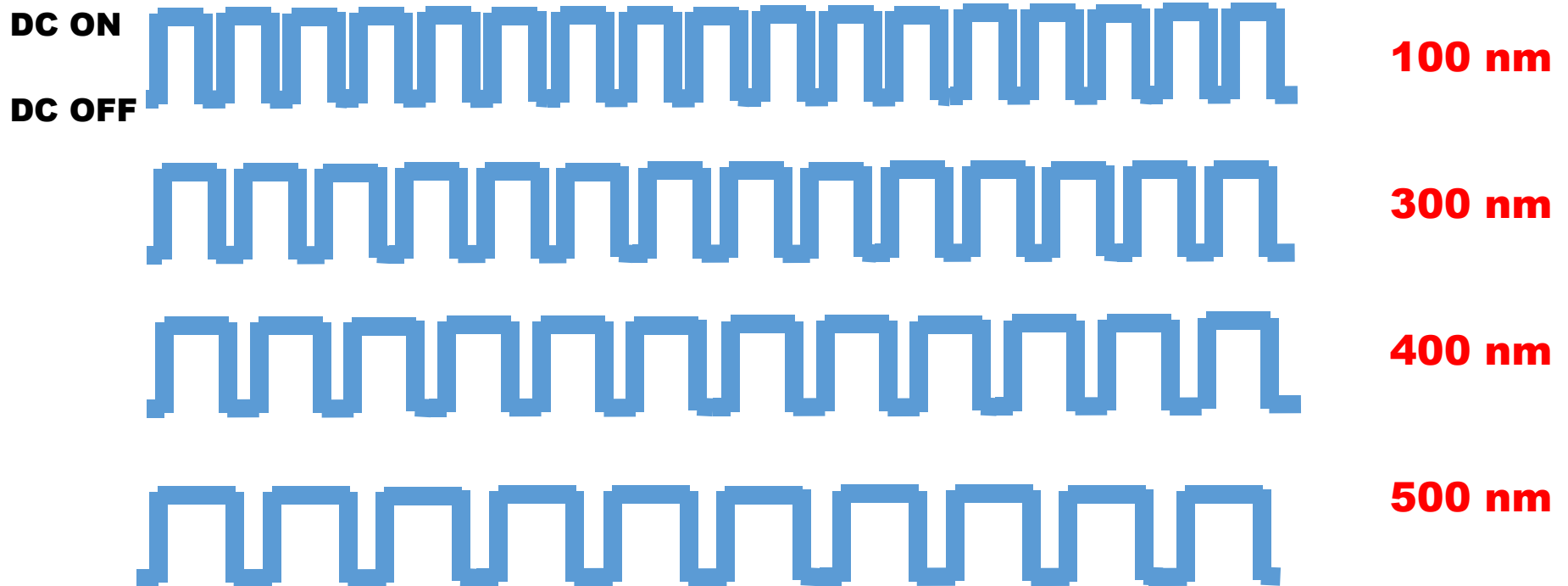
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Experimental results **on 6 GHz cavities**

6 GHz Cavity @ 1,8 K



Deposition of several cavities, by modulating the **thickness of single layer**



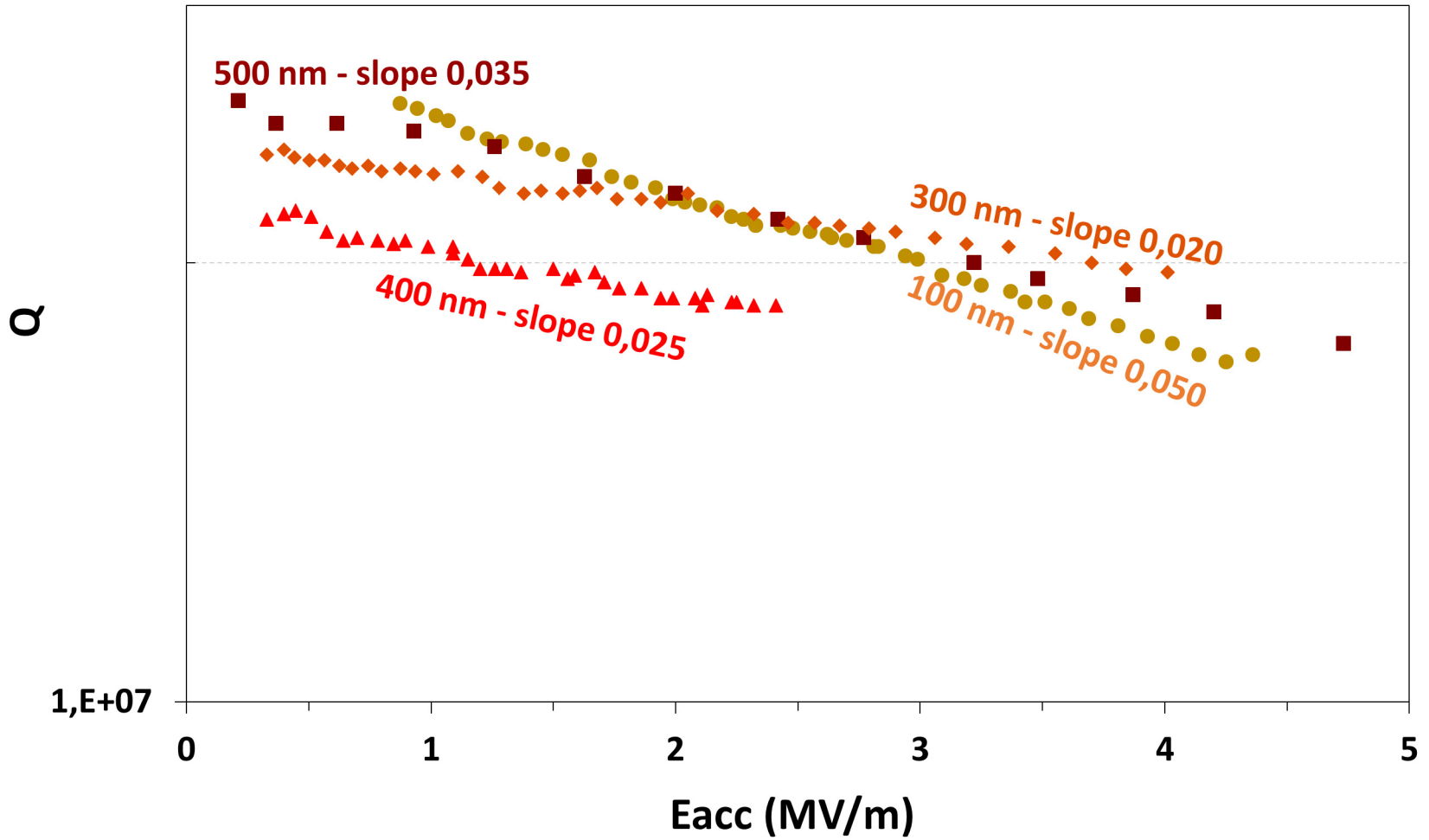
Total thickness of all cavities is kept constant to 70 μm

A key parameter: **the single layer thickness**

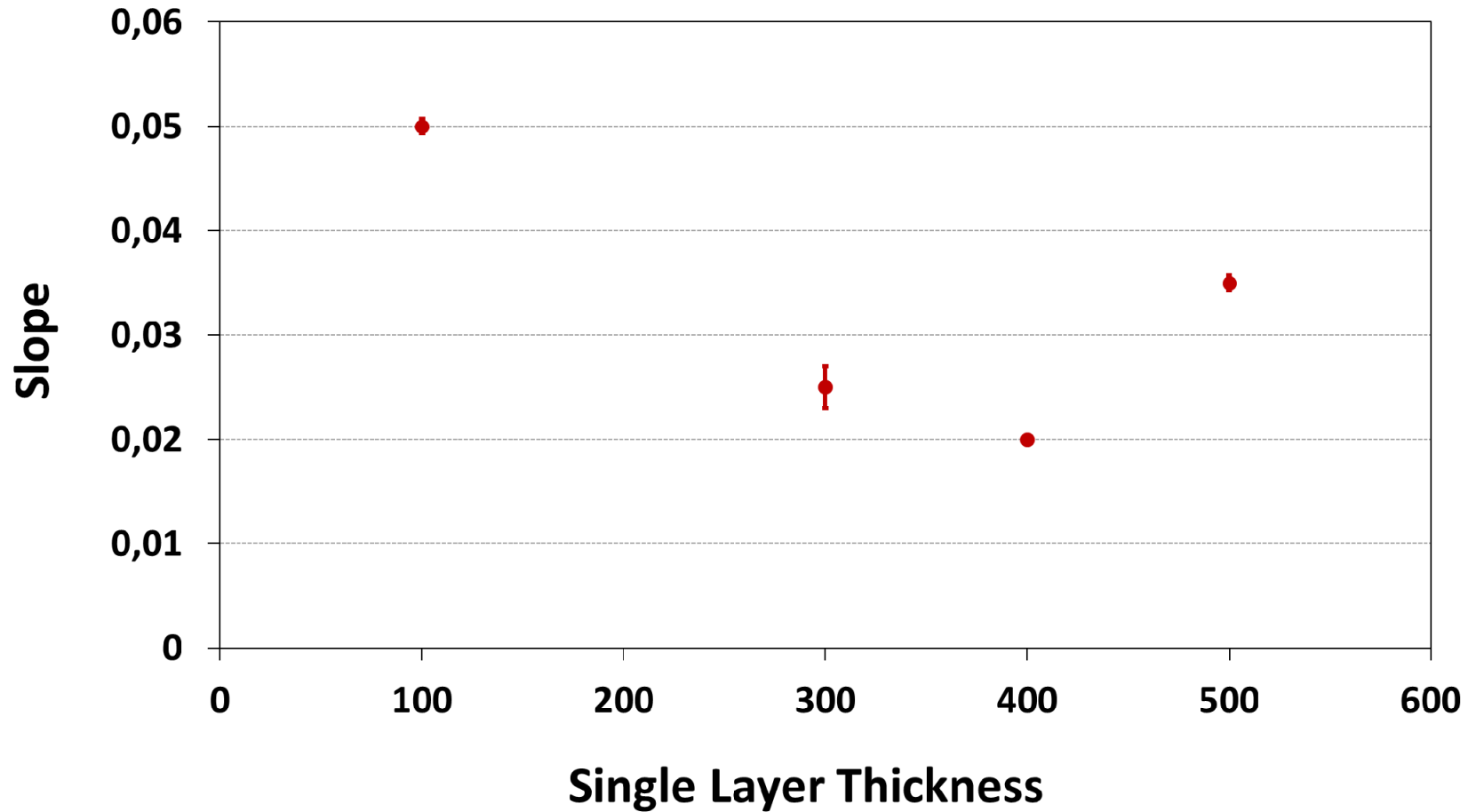
**The single layer cannot be too thin,
because: T_c and RRR increase with
thickness**

**The single layer cannot be too large,
because: Stress will increase with thickness**

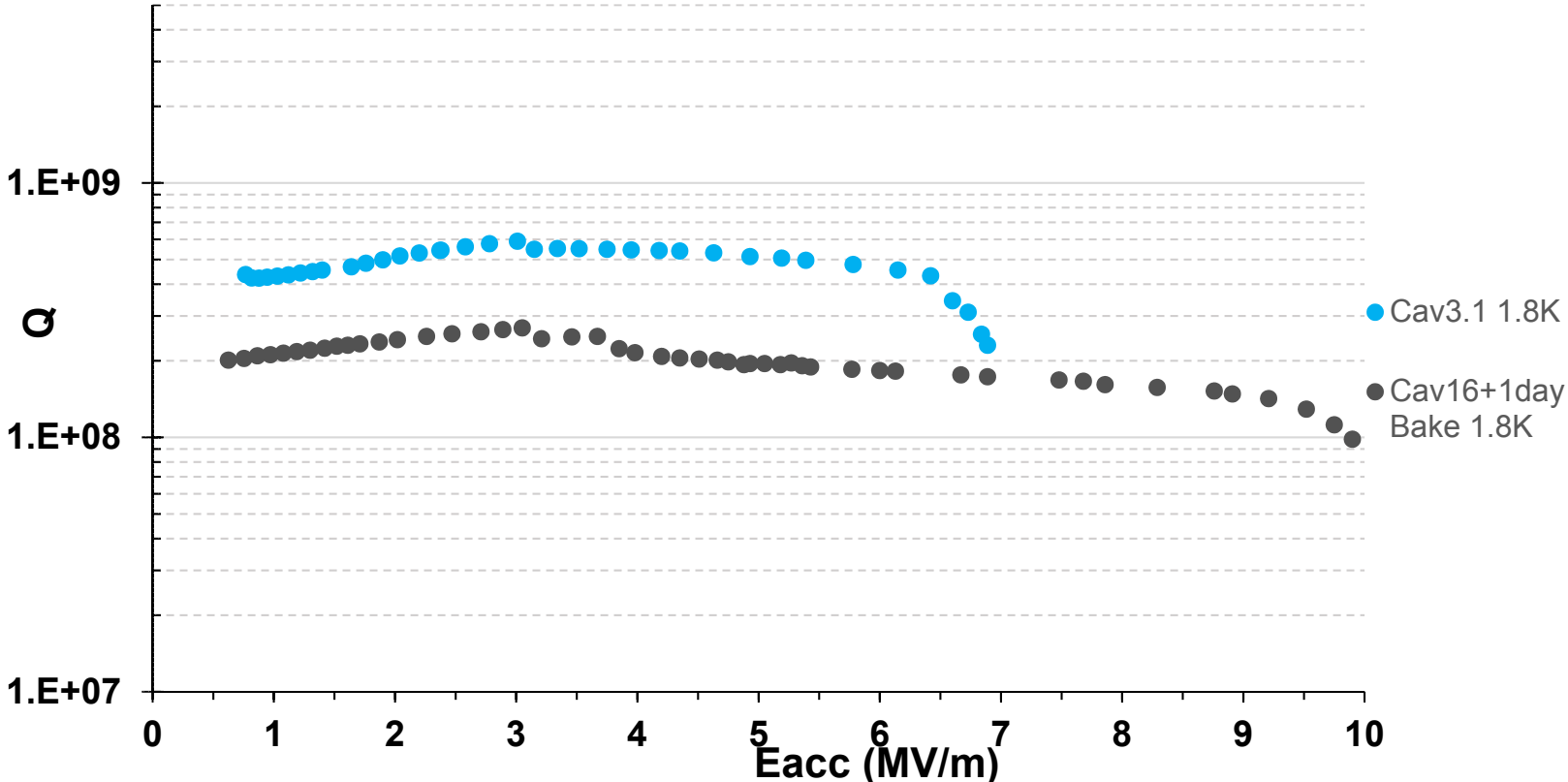
6 GHz Multilayer @ 4,2 K



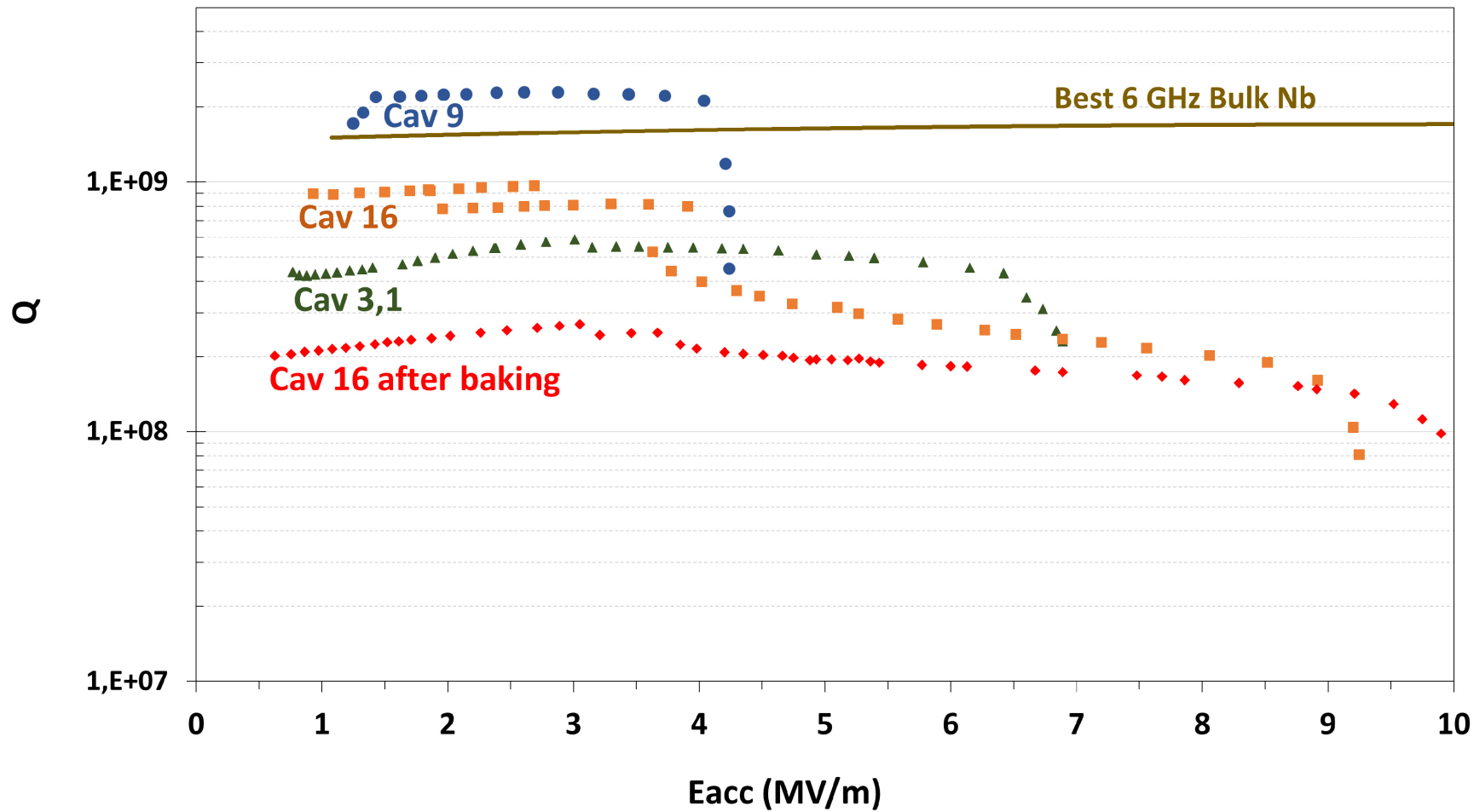
Curve Slope in 6 GHz Multilayer @ 4,2 K



Nb/Cu 6 GHz cavities



6 GHz @ 1,8 K



**In the R&D for flat-Q cavities,
Thick films are not the arrival point,
but just the way!**

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Once optimized thick films,

the way will consist in reducing the thickness,



in order to arrive to deposit again

as thin as possible films



The 8th International Workshop on:

**THIN FILMS AND NEW IDEAS FOR PUSHING
THE LIMITS OF RF SUPERCONDUCTIVITY**

October 8 - 10, 2018

Legnaro National Laboratories – INFN (Padua) ITALY